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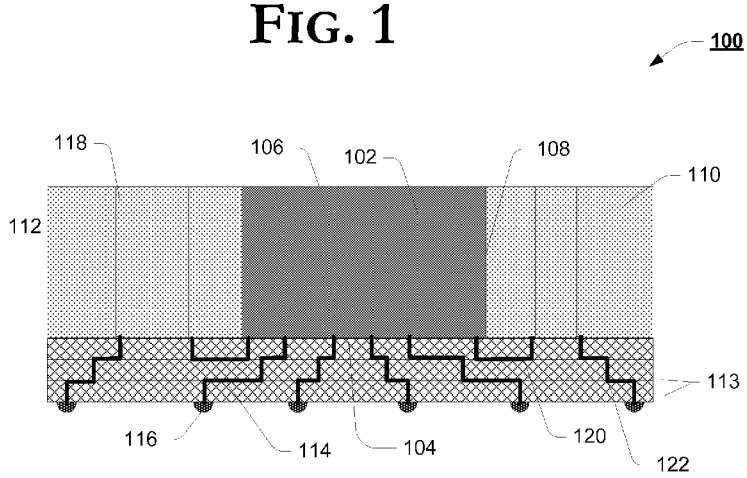
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(54) Title: PACKAGE ON PACKAGE USING A BUMP-LESS BUILD UP LAYER (BBUL) PACKAGE

FIG. 1



(57) Abstract: In some embodiments, package on package using a bump-less build up layer (BBUL) package is presented. In this regard, an apparatus is introduced comprising a microelectronic die having an active surface, an inactive surface parallel to said active surface, and at least one side, an encapsulation material adjacent said at least one microelectronic die side, wherein said encapsulation material includes a bottom surface substantially planar to said microelectronic die active surface and a top surface substantially planar to said microelectronic die inactive surface, a through via connection in said encapsulation material extending from said top surface to said bottom surface, a first dielectric material layer disposed on at least a portion of said microelectronic die active surface and said encapsulation material surface, a plurality of build-up layers disposed on said first dielectric material layer, and a plurality of conductive traces disposed on said first dielectric material layer and said build-up layers and in electrical contact with said microelectronic die active surface. Other embodiments are also disclosed and claimed.

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